

**QT-Brightek Chip LED Series**

**SMD 0603 LED**

**Part No.: QBLP601-2IW3-2897**

**3: 3mA**

**2897: High Brightness Version**



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## Introduction

### Feature:

- Yellow diffused lens
- Package in tape and reel
- Ultra bright 0603 LED package
- InGaN technology
- Viewing angle: 140° typ.
- Height profile: 0.6mm

### Application:

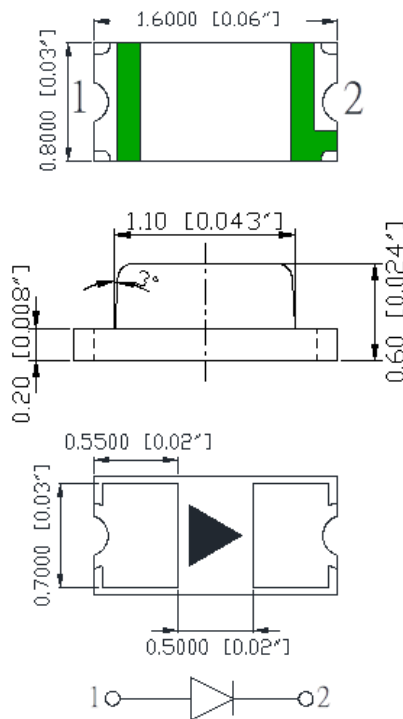
- Status indication
- Back lighting application

### Certification & Compliance:

- ISO9001
- RoHS Compliant



### Dimension:



Units: mm / tolerance = +/-0.1mm

## Electrical / Optical Characteristic (Ta=25 °C)

Product	Color	I <sub>F</sub> (mA)	V <sub>F</sub> (V)			CIE Coordinate	I <sub>V</sub> (mcd)		
			Min.	Typ.	Max.	Typ.	Min.	Typ.	Max.
QBLP601-2IW3-2897	White	3	2.8	3.0	3.4	X=0.29 Y=0.296	80	130	250

## Absolute Maximum Rating

Chip Material	P <sub>d</sub> (mW)	I <sub>F</sub> (mA)	I <sub>FP</sub> (mA)*	V <sub>R</sub> (V)	T <sub>OP</sub> (°C)	T <sub>ST</sub> (°C)	T <sub>SO L</sub> (°C)**
InGaN	102	30	100	5	-40 ~ +80	-40 ~ +85	260

\*Duty 1/10 @ 1kHz

\*\*IR Reflow for no more than 10 sec @ 260 °C

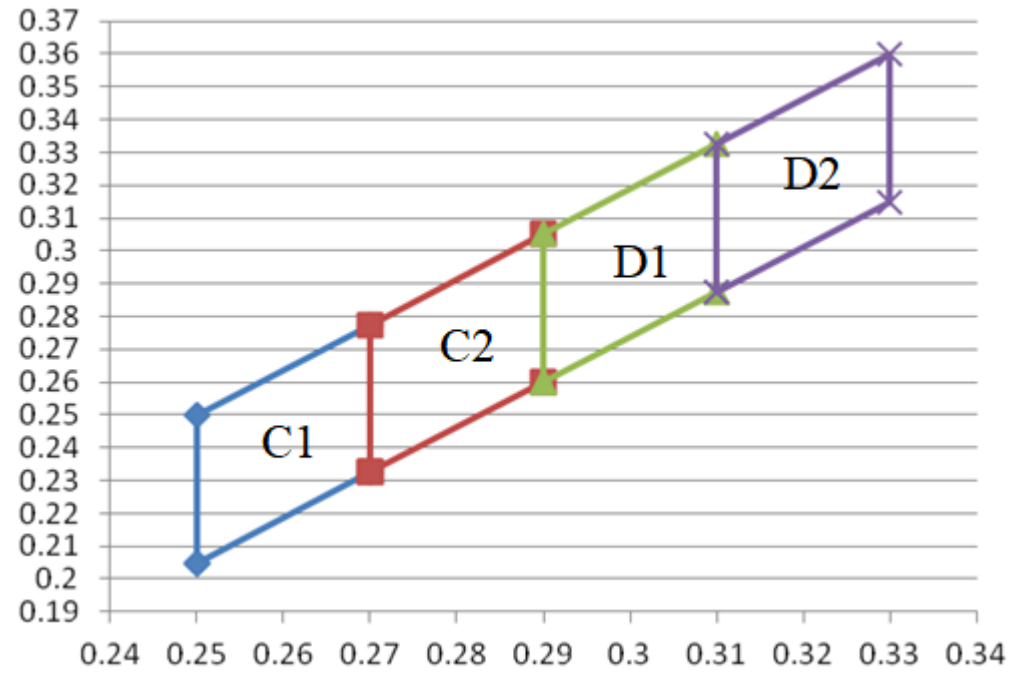
## Forward Voltage V<sub>F</sub> @ I<sub>F</sub>=3mA

Bin	Min.	Max.	Unit
e	2.5	2.8	V
f	2.8	3.1	
g	3.1	3.4	

## Luminous Intensity I<sub>V</sub> @ I<sub>F</sub>=3mA

Bin	Min.	Max.	Unit
I	80	100	mcd
J	100	125	
K	125	160	
L	160	200	
M	200	250	

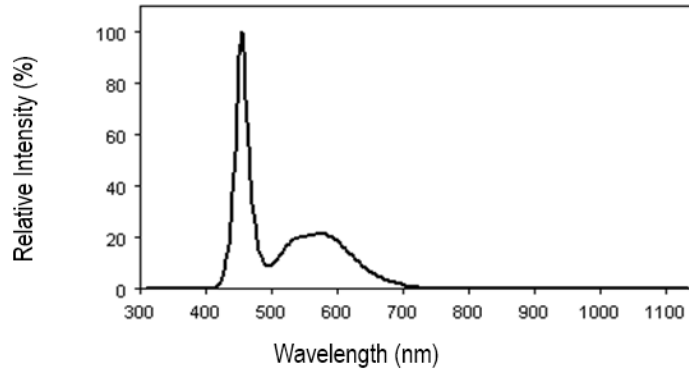
## CIE Chromaticity Diagram



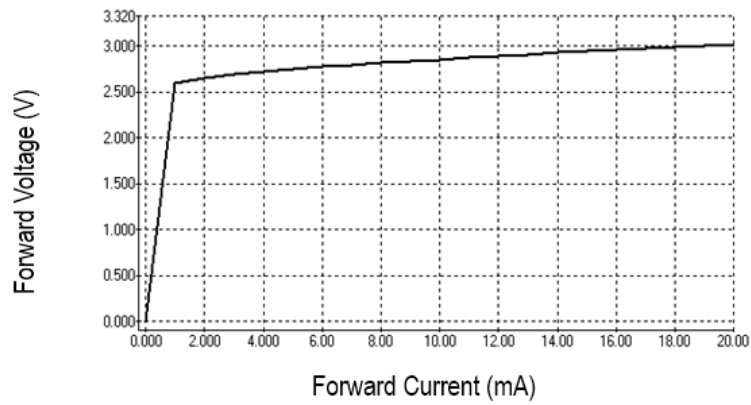
Rank	Chromaticity coordinates				
		X	Y	X	Y
C1	X	0.25	0.205	0.27	0.2325
	Y	0.25	0.2775	0.25	0.2775
C2	X	0.27	0.2325	0.29	0.26
	Y	0.2775	0.2775	0.305	0.2775
D1	X	0.29	0.26	0.31	0.2875
	Y	0.29	0.305	0.3325	0.305
D2	X	0.31	0.2875	0.33	0.315
	Y	0.31	0.3325	0.36	0.3325

## Characteristic Curves

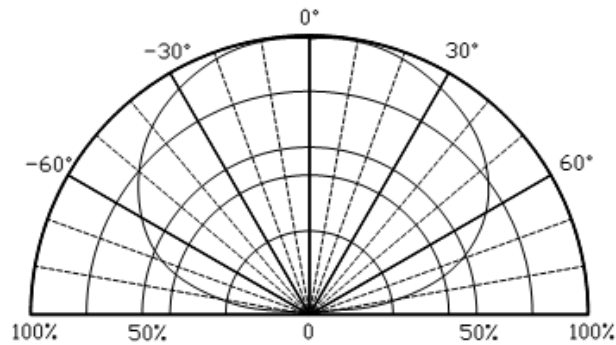
Relative Intensity vs. Wavelength



Forward Current vs. Forward Voltage

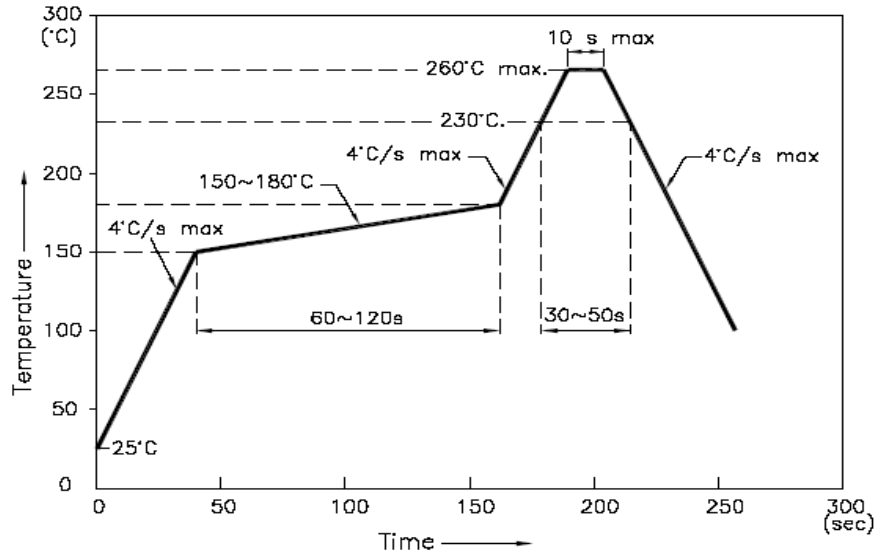


Directive Characteristics

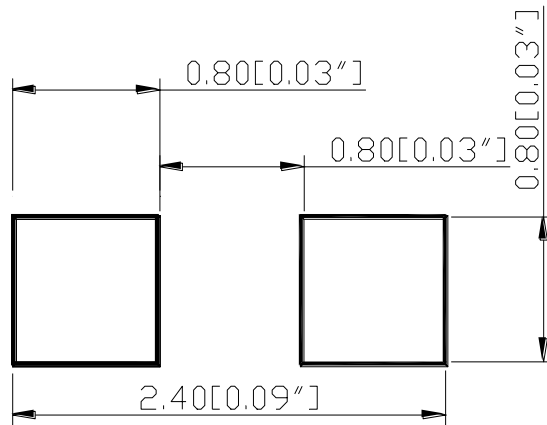


## Solder Profile & Footprint

-The recommended soldering profile is as follows (temperatures indicated are as measured on the surface of the LED resin):



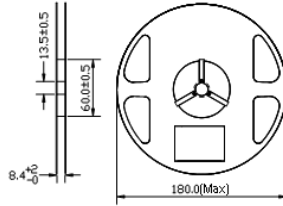
### Recommended Pad Layout



Units: mm

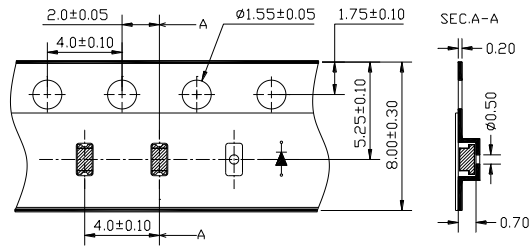
## Packing

### Reel Dimension:



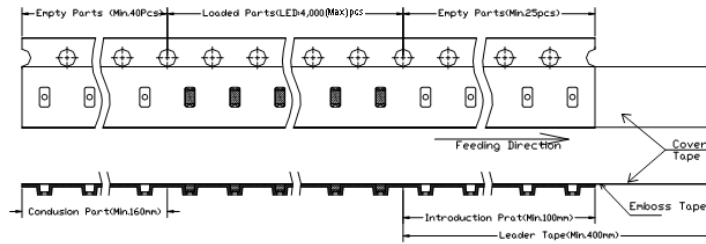
Unit: mm

### Tape Dimension:

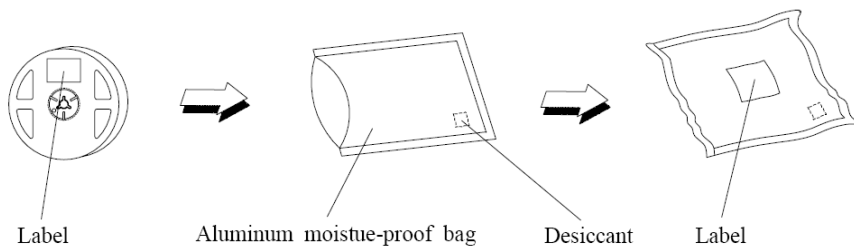


Unit: mm

### Arrangement of Tape:



### Packaging Specifications:





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## Ordering Information

Orderable Part #	Spec Range	Quantity per reel
QBLP601-2IW3-2897	Iv=130mcd typ. @ If=3mA / CIE Coordinate: (X=0.29, Y=0.296) typ.	4,000 units



## Revision History

Description:	Revision #	Revision Date
New Release of QBLP601-2IW3-2897	V1.0	08/25/2025

## Disclaimer

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2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

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